



THE BIG DEAL

- Stop Band Rejection, 40 dB Typ.
- Rugged, Ceramic Construction
- Stop Band Rejection, 35 dB Typ.
- Small size, 1210



Generic photo used for illustration purposes only

CASE STYLE: JV1210C-13

+RoHS Compliant

The +Suffix identifies RoHS Compliance.
See our website for methodologies and qualifications

APPLICATIONS

- Communications, Radar, EW and ECM Defense Systems

PRODUCT OVERVIEW

LFCV-2202+ is a miniature low temperature co-fired ceramic (LTCC) low pass filter with a DC to 22 GHz passband supporting a variety of applications. This model provides 1.7 dB typical insertion loss over a wide band due to its rugged monolithic construction. Housed in a small 1210 ceramic form factor, the filter is ideal for dense signal chain PCB layouts where it complements MMIC size and performance. The LTCC fabrication process assures minimal RF performance variation while delivering a product that is well suited for environmental extremes of high humidity and temperature.

KEY FEATURES

Feature	Advantages
Ultra-wide Stopband	The LTCC lowpass filter provides a very good stopband rejection to 51 GHz suitable for high end applications.
LTCC Construction	Provides repeatable performance in a rugged, ceramic package well suited for tough environments such as high humidity and temperature extremes.
Cost effective	LTCC is scalable technology that is cost effective due to ease of production in high volume.
Small footprint (1210)	Allows for high layout density of circuit boards, while minimizing effects of parasitics.
Surface Mountable	Suitable for very high-volume automated assembly processes.



LTCC SMT

Low Pass Filter

LFCV-2202+

Mini-Circuits

50Ω

DC to 22 GHz

ELECTRICAL SPECIFICATIONS^{1,2} AT 25°C

Parameter		F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Passband	Insertion Loss	F1 - F2	DC-22	—	1.7	2.3	dB
	Return Loss	F1 - F2	DC-22	—	14	—	dB
Stop Band	Insertion Loss	F3 - F4	29.8-42	30	40	—	dB
		F4 - F5	42-48	25	35	—	
		F5 - F6	48-51	—	25	—	

1. Measured on Mini-Circuits Test Board TB-LFCV-2202C+ with the connector and feedline effects de-embedded using the 2XThru IEEE P370 method

2. DC Blocking capacitors are required in Applications where DC voltage and/or current is present at either RF1 or RF2 ports.

Please contact Mini-Circuits for alternatives if DC pass from RF1-RF2 is required.

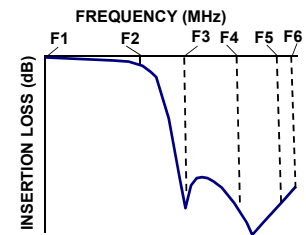
ABSOLUTE MAXIMUM RATINGS¹

Parameter	Ratings
Operating Temperature	-55°C to +125°C
Storage Temperature	-55°C to +125°C
RF Power Input ²	1W max.

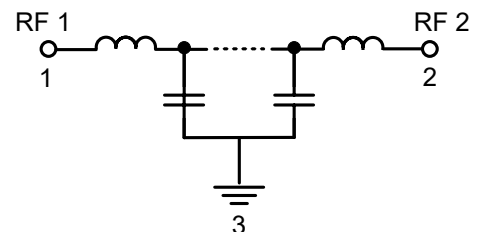
1. Permanent damage may occur if any of these limits are exceeded.

2. Derate linearly to 0.5 W at 125°C.

TYPICAL FREQUENCY RESPONSE



FUNCTIONAL SCHEMATIC





Mini-Circuits®

LTCC SMT

Low Pass Filter

50Ω DC to 22 GHz

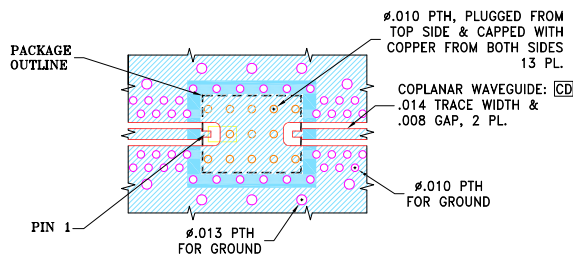
LFCV-2202+

PAD CONNECTIONS

RF 1	1
RF 2	2
GROUND	3

PRODUCT MARKING: VT

SUGGESTED PCB LAYOUT (PL-743)



STACK-UP DIAGRAM

PTH	-COPPER LAYER 1 (L1), .5 OZ.
HOLE	-CORE 1, .0079 MEGTRON-7 R5785(N/GN)
	-COPPER LAYER 2 (L2), .5 OZ.
	-PREPREG, .0035 (89µm) MEGTRON-7 R5680(N/GN), CLOTH STYLE:1078
	-PREPREG, .0035 (89µm) MEGTRON-7 R5680(N/GN), CLOTH STYLE:1078
	-COPPER LAYER 3 (L3), .5 OZ.
	-CORE 2, .0079 MEGTRON-7 R5785(N/GN)
	-COPPER LAYER 4 (L4), .5 OZ.

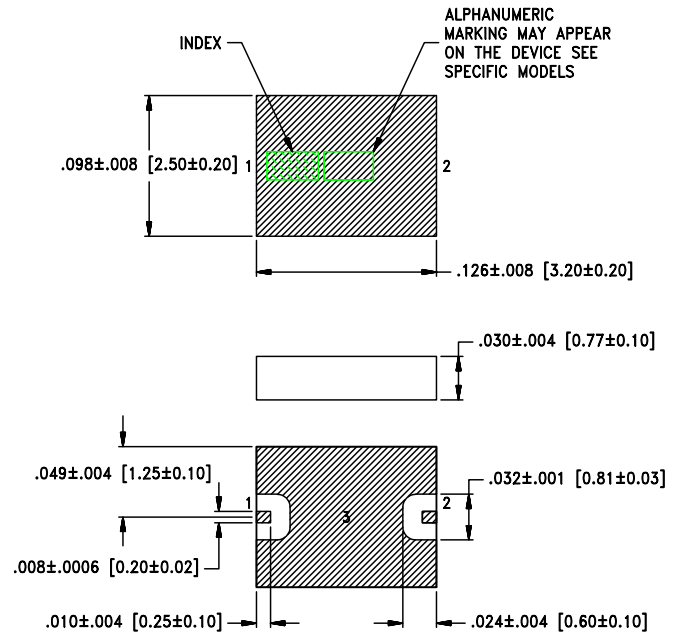
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2. PTH PRESENT FROM COPPER LAYER 1 TO COPPER LAYER 4.
3. INDICATED ON TOP VIEW PTH'S ARE PLUGGED WITH EPOXY AND CAPPED WITH COPPER FROM TOP SIDE.
4. L2, L3 AND L4 ARE CONTINUOUS GROUND PLANES.

NOTES:

1. PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
2. TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR MEGTRON-7 R-5785(N/GN), WITH DIELECTRIC THICKNESS .0079; COPPER: 1/2 OZ. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

	DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)
	DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

OUTLINE DRAWING



Weight: .024 grams

Dimensions are in inches [mm]. Tolerances: 2 Pl. ±.010; 3 Pl. ±.005

OUTLINE DIMENSIONS (Inches mm)

A	B	C	D	E	F	G	H	wt
.126	.098	.030	.049	.008	.010	.024	.032	grams
3.2	2.5	0.8	1.2	0.20	0.3	0.6	0.8	0.030

TAPE & REEL INFORMATION: F74



Mini-Circuits

CERAMIC

Low Pass Filter

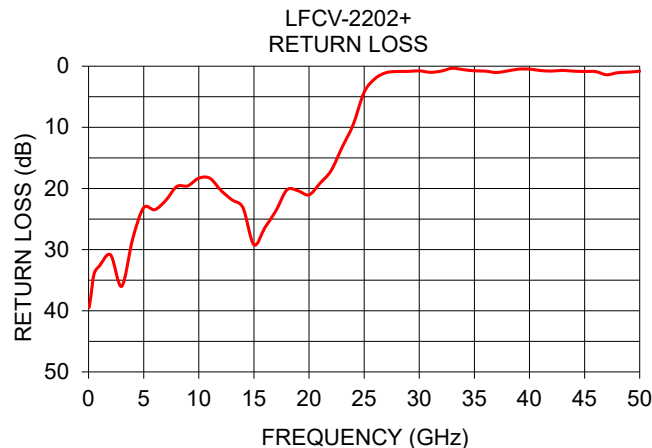
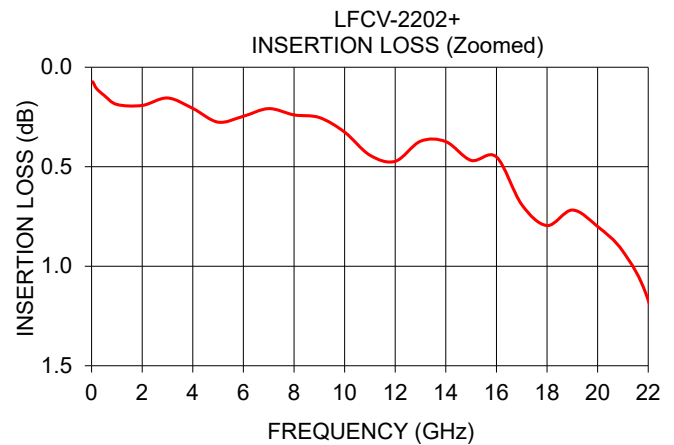
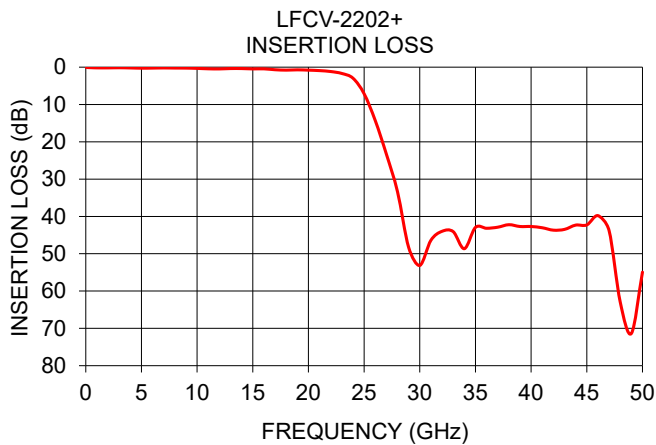
LFCV-2202+

50Ω

DC to 22 GHz

TYPICAL PERFORMANCE DATA AT 25°C

Frequency (GHz)	Insertion Loss (dB)	Return Loss (dB)
0.05	0.07	39.47
0.5	0.14	33.97
1.0	0.19	32.63
5.0	0.28	23.13
6.0	0.25	23.48
7.0	0.21	21.96
8.0	0.24	19.68
9.0	0.25	19.57
10	0.33	18.32
15	0.47	29.21
20	0.80	21.04
25	7.13	4.26
30	53.14	0.75
40	42.70	0.48
50	54.92	0.82



NOTES

- Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
- The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard. Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html



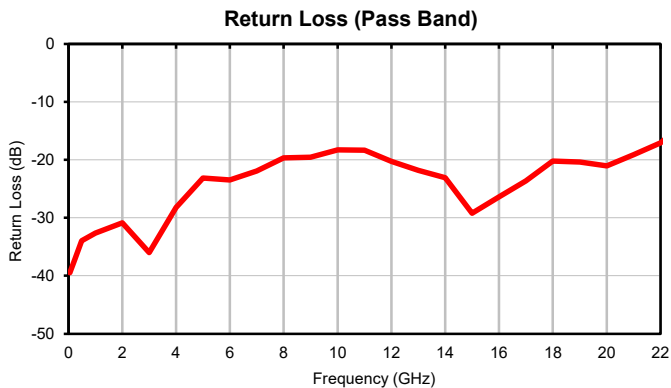
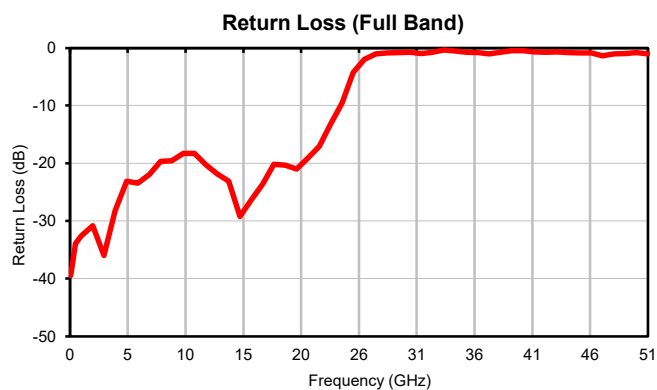
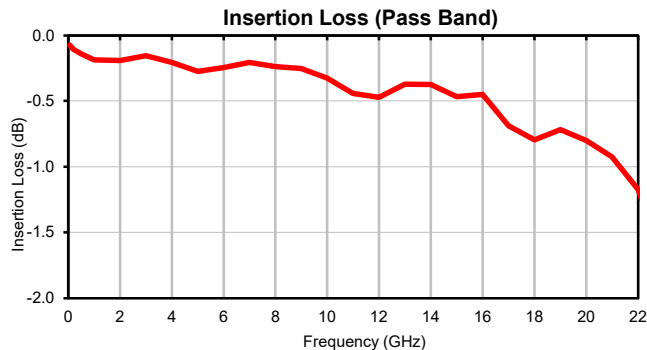
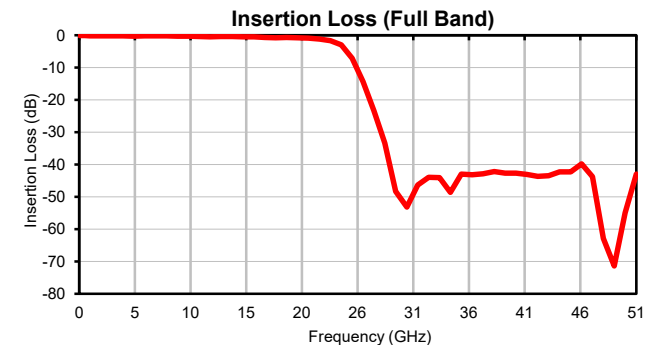
Low Pass Filter

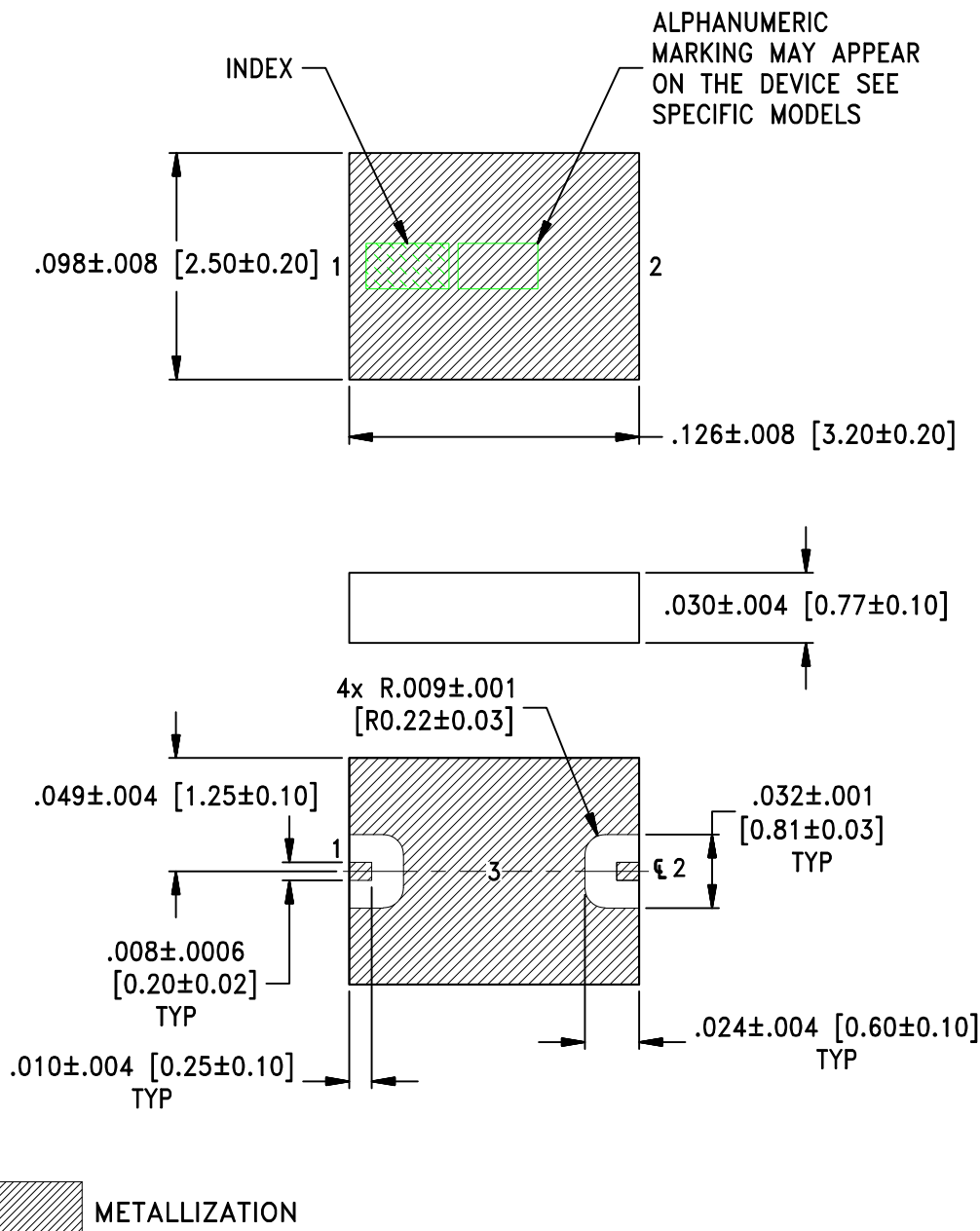
LFCV-2202+

Typical Performance Data

FREQUENCY (GHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
0.05	0.07	39.47
0.2	0.11	37.72
0.5	0.14	33.97
1.0	0.19	32.63
2.0	0.19	30.87
3.0	0.15	36.01
4.0	0.21	28.25
5.0	0.28	23.13
6.0	0.25	23.48
7.0	0.21	21.96
8.0	0.24	19.68
9.0	0.25	19.57
10.0	0.33	18.32
11.0	0.44	18.32
12.0	0.47	20.30
13.0	0.37	21.85
14.0	0.37	23.11
15.0	0.47	29.21
16.0	0.45	26.39
17.0	0.69	23.64
18.0	0.80	20.22
19.0	0.72	20.37
20.0	0.80	21.04
21.0	0.93	19.14
22.0	1.17	17.09
23.0	1.69	13.27
24.0	2.96	9.59
25.0	7.13	4.26
26.0	14.32	2.02
27.0	23.33	1.06
28.0	33.41	0.87
29.0	48.31	0.85
30.0	53.14	0.75
31.0	46.39	1.00
32.0	43.99	0.80
33.0	44.08	0.34
34.0	48.65	0.56
35.0	42.95	0.76
36.0	43.18	0.81
37.0	42.89	1.03
38.0	42.22	0.78
39.0	42.70	0.48
40.0	42.70	0.48
41.0	43.04	0.71
42.0	43.68	0.80
43.0	43.47	0.69
44.0	42.33	0.81
45.0	42.27	0.87
46.0	39.79	0.88
47.0	43.79	1.40
48.0	62.92	1.06
49.0	71.37	0.97
50.0	54.92	0.82
51.0	42.98	1.03

Typical Performance Curves





Weight: .024 grams

Dimensions are in inches (mm). Tolerances: 2 Pl. ± .010; 3 Pl. ± .005

Notes:

1. Open style, Ceramic base.
2. Termination finish: **as shown below or indicated on Data Sheet.**
For RoHS Case Styles: Gold plate over Nickel plate. All models, (+) suffix.
3. Pad tolerance is non-cumulative. Minimum spacing between each pad is .004.



P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F74

DEVICE ORIENTATION IN T&R

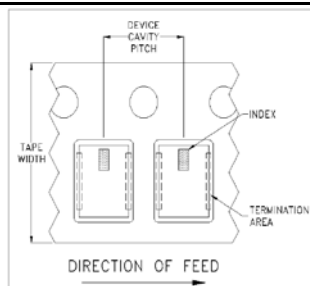


ILLUSTRATION 1

Applicable Case Styles

GE0805C-1
GE0805C-1AP
JV1210C-1
GU2939

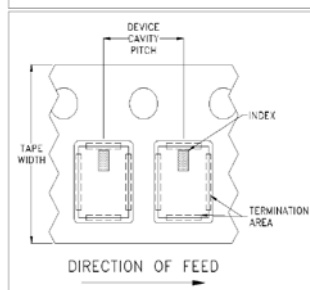


ILLUSTRATION 2

Applicable Case Styles

JV1210C
JV1210C-2
JV1210C-3
JV1210C-4
JV1210C-5
JV1210C-6
JV1210C-11

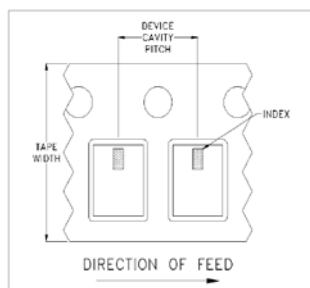


ILLUSTRATION 3

Applicable Case Styles

JC0603C-8
JV1210C-7
JV1210C-8
JV1210C-9
JV1210C-10
JV1210C-13
GE0805C-13

Tape Width, mm	Device Cavity Pitch, mm	Real Size, inches	Devices per Reel	
8	4	7	Small quantity standards (see note)	20
				50
				100
				200
				500
				1000
			Standard	2000
				4000

Note: Small reel availability varies by model. Refer to pricing and availability on individual model dashboard.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



INTERNET <http://www.minicircuits.com>

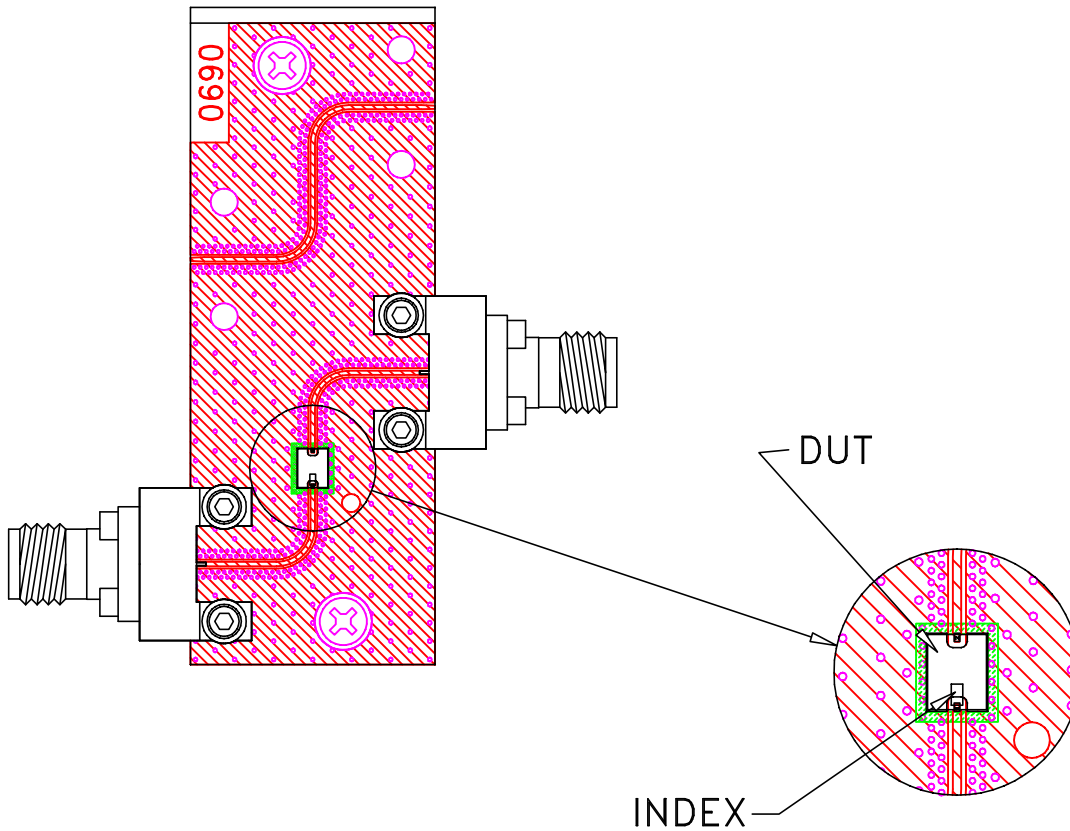
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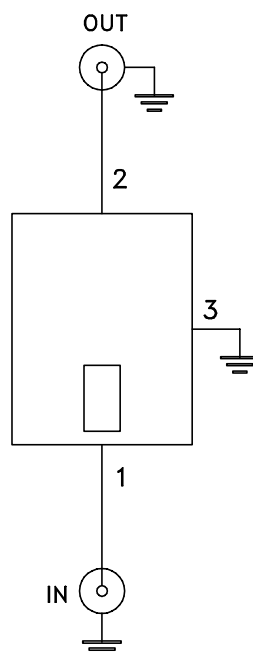
Mini-Circuits ISO 9001 & ISO 14001 Certified

THIRD ANGLE PROJECTION		REVISIONS													
		REV	ECN No.	DESCRIPTION	DATE	DR	AUTH								
		OR	ECO-015970	NEW RELEASE	12/06/22	GF	IL								
SUGGESTED MOUNTING CONFIGURATION FOR JV1210C-13 CASE STYLE															
STACK-UP DIAGRAM															
<table><tr><td>-COPPER LAYER 1(L1), .5 OZ.</td></tr><tr><td>-CORE 1, .0079 MEGTRON-7 R5785(N/GN)</td></tr><tr><td>-COPPER LAYER 2 (L2), .5 OZ.</td></tr><tr><td>-PREPREG, .0035 (89um) MEGTRON-7 R5680(N/GN), CLOTH STYLE:1078</td></tr><tr><td>-PREPREG, .0035 (89um) MEGTRON-7 R5680(N/GN), CLOTH STYLE:1078</td></tr><tr><td>-COPPER LAYER 3 (L3), .5 OZ.</td></tr><tr><td>-CORE 2, .0079 MEGTRON-7 R5785(N/GN)</td></tr><tr><td>-COPPER LAYER 4 (L4), .5 OZ.</td></tr></table>								-COPPER LAYER 1(L1), .5 OZ.	-CORE 1, .0079 MEGTRON-7 R5785(N/GN)	-COPPER LAYER 2 (L2), .5 OZ.	-PREPREG, .0035 (89um) MEGTRON-7 R5680(N/GN), CLOTH STYLE:1078	-PREPREG, .0035 (89um) MEGTRON-7 R5680(N/GN), CLOTH STYLE:1078	-COPPER LAYER 3 (L3), .5 OZ.	-CORE 2, .0079 MEGTRON-7 R5785(N/GN)	-COPPER LAYER 4 (L4), .5 OZ.
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UNLESS OTHERWISE SPECIFIED															
INITIALS		DATE													
DRAWN		GF		12/06/22											
CHECKED		IL		12/06/22											
APPROVED		IL		12/06/22											
DIMENSIONS ARE IN INCHES															
TOLERANCES ON:															
2 PL DECIMALS ±															
3 PL DECIMALS ± .005															
ANGLES ±															
FRACTIONS ±															
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ASHEETA1.DWG REV:A		DATE:01/12/95													
SIZE		CODE IDENT		DRAWING NO:		REV:									
A		15542		98-PL-743		OR									
FILE:		98PL743		SCALE:		SHEET:									
				8:1		1 OF 1									

Evaluation Board and Circuit



TB-LFCV-2202C+



Schematic Diagram

1. 50 Ohm 1.85 End Launch Female connectors.
2. PCB Material: Megtron 7(N) or equivalent,
Dielectric Constant=3.4, Thickness=.0079 inch.

 Mini-Circuits®



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Solder Reflow Heat	Sn-Pb Eutectic Process 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020C, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, Test B,B1, 95% Coverage
Thermal Shock	-55° to +125°C, 15 min dwell,250 cycles	MIL-STD-202, Method 107
Bend Test	1mm, deflection for 5 seconds Span of bending: 2.75"	--
High Temp Storage	125°C to 1000 Hrs	---